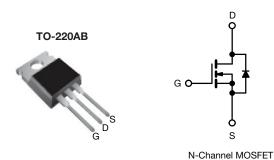


Power MOSFET



PRODUCT SUMMARY				
V _{DS} (V)	200			
$R_{DS(on)}(\Omega)$	$V_{GS} = 5.0 \text{ V}$	0.18		
Q _g max. (nC)	66			
Q _{gs} (nC)	9.0			
Q _{gd} (nC)	38			
Configuration	Single			

FEATURES

- Dynamic dV/dt rating
- · Repetitive avalanche rated
- · Logic-level gate drive
- R_{DS(on)} specified at V_{GS} = 4 V and 5 V
- Fast switching
- · Ease of paralleling
- Simple drive requirements
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

Note

* This datasheet provides information about parts that are RoHS-compliant and / or parts that are non RoHS-compliant. For example, parts with lead (Pb) terminations are not RoHS-compliant. Please see the information / tables in this datasheet for details

DESCRIPTION

Third generation power MOSFETs from Vishay provides the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost effectiveness.

The TO-220AB package is universally preferred for all commercial-industrial applications at power dissipation levels to approximately 50 W. The low thermal resistance and low package cost of the TO-220AB contribute to its wide acceptance throughout the industry.

ORDERING INFORMATION			
Package	TO-220AB		
Lead (Pb)-free	IRL640PbF		
Lead (Pb)-free and halogen-free	IRL640PbF-BE3		

ABSOLUTE MAXIMUM RATINGS (T _C	= 25 °C, un	ess otherwis	se noted)			
PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-source voltage			V_{DS}	200	V	
Gate-source voltage			V_{GS}	± 10	7 v	
Continuous drain current	V _{GS} at 5 V	$T_C = 25 ^{\circ}C$ $T_C = 100 ^{\circ}C$	- I _D	17		
		T _C = 100 °C		11	Α	
Pulsed drain current ^a			I _{DM}	68		
Linear derating factor				1.0	W/°C	
Single pulse avalanche energy ^b			E _{AS}	580	mJ	
Repetitive avalanche current a			I _{AR}	10	Α	
Repetitive avalanche energy ^a			E _{AR}	13	mJ	
Maximum power dissipation	T _C =	25 °C	P _D	125	W	
Peak diode recovery dV/dt ^c			dV/dt	5.0	V/ns	
Operating junction and storage temperature range			T _J , T _{stg}	-55 to +150	°C	
Soldering recommendations (peak temperature) ^d	For 10 s			300		
Mounting torque	6-32 or M3 screw			10	lbf ⋅ in	
				1.1	N·m	

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)
- b. V_{DD} = 50 V, starting T_J = 25 °C, L = 3.0 mH, R_q = 25 Ω I_{AS} = 17 A (see fig. 12)
- c. $I_{SD} \le 17$ A, $dI/dt \le 150$ A/ms, $V_{DD} \le V_{DS}$, $T_J \le 150$ °C



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d. 1.6 mm from case

THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	TYP.	MAX.	UNIT	
Maximum junction-to-ambient	R _{thJA}	-	62		
Case-to-sink, flat, greased surface	R _{thCS}	0.50	-	°C/W	
Maximum junction-to-case (drain)	R _{thJC}	-	1.0		

PARAMETER	SYMBOL	TEST	MIN.	TYP.	MAX.	UNIT	
Static		•			<u></u>		
Drain-source breakdown voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		200	-	-	V
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	Reference	Reference to 25 °C, I _D = 1 mA		0.27	-	V/°C
Gate-source threshold voltage	V _{GS(th)}	$V_{DS} = V$	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$		-	2.0	V
Gate-source leakage	I _{GSS}	V _{GS} = ± 10		-	-	± 100	nA
Zava gata valtaga duain avuvant		V _{DS} = 200 V, V _{GS} = 0 V			25		
Zero gate voltage drain current	I _{DSS}	V _{DS} = 160 V, \	/ _{GS} = 0 V, T _J = 125 °C	-	-	250	μA
Dynin agures on state registance	Б	V _{GS} = 5.0 V	I _D = 10 A ^b	-	-	0.18	Ω
Drain-source on-state resistance	R _{DS(on)}	V _{GS} = 4.0 V	I _D = 8.5 A ^b	-	-	0.27	
Forward transconductance	9 _{fs}	V _{DS} = 50 V, I _D = 10 A ^b		16	-	-	S
Dynamic							
Input capacitance	C _{iss}	$V_{GS} = 0 \text{ V},$ $V_{DS} = 25 \text{ V}$ f = 1.0 MHz, see fig. 5		-	1800	-	pF
Output capacitance	C _{oss}			-	400	-	
Reverse transfer capacitance	C _{rss}			-	120	-	
Total gate charge	Qg			-	-	66	nC
Gate-source charge	Q_{gs}	$V_{GS} = 5.0 \text{ V}$	$I_D = 17 \text{ A}, V_{DS} = 160 \text{ V},$ see fig. 6 and 13 b	-	-	9.0	
Gate-drain charge	Q_{gd}		see lig. 0 and 13	-	-	38	
Turn-on delay time	t _{d(on)}			-	8.0	-	
Rise time	t _r	V_{DD} = 100 V, I_{D} = 17 A R_{g} = 4.6 Ω , R_{D} = 5.7 Ω , see fig. 10 b		-	83	-	ns
Turn-off delay time	t _{d(off)}			-	44	-	
Fall time	t _f			-	52	-	
Internal drain inductance	L _D	Between lead, 6 mm (0.25") from package and center of die contact		-	4.5	-	-11
Internal source inductance	L _S			-	7.5	-	- nH
Gate input resistance	Rq	f = 1 MHz, open drain		0.3	-	1.2	Ω
Drain-Source Body Diode Characteristic							
Continuous source-drain diode current	I _S	MOSFET symbo	MOSFET symbol showing the		-	17	^
Pulsed diode forward current ^a	I _{SM}	integral reverse p - n junction diode		-	-	68	- A
Body diode voltage	V _{SD}	$T_J = 25 ^{\circ}\text{C}, I_S = 17 \text{A}, V_{GS} = 0 \text{V}^{ \text{b}}$		-	-	2.0	V
Body diode reverse recovery time	t _{rr}	- T _J = 25 °C, I _F = 17 A, dl/dt = 100 A/μs b		-	310	470	ns
Body diode reverse recovery charge	Q_{rr}			-	3.2	4.8	μC
Forward turn-on time	t _{on}	Intrinsic turn	-on time is negligible (turr	on is do	minated b	y L _S and	L _D)

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)
- b. Pulse width $\leq 300~\mu s;~duty~cycle \leq 2~\%$



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

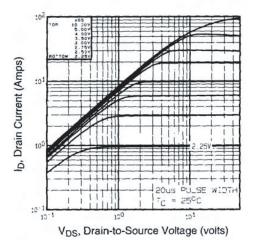


Fig. 1 - Typical Output Characteristics, T_C = 25 $^{\circ}C$

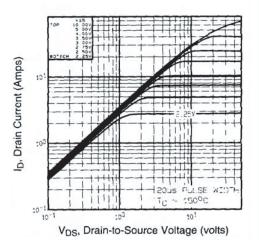


Fig. 2 - Typical Output Characteristics, T_C = 150 °C

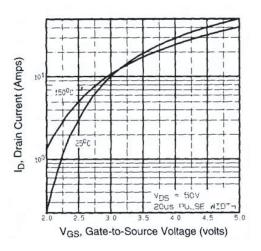


Fig. 3 - Typical Transfer Characteristics

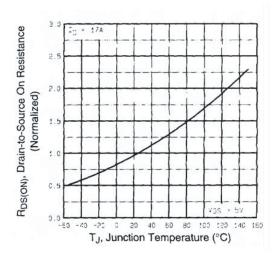


Fig. 4 - Normalized On-Resistance vs. Temperature



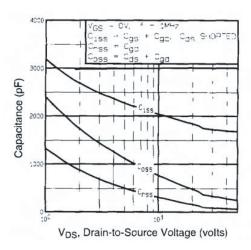


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

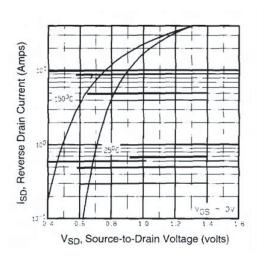


Fig. 7 - Typical Source-Drain Diode Forward Voltage

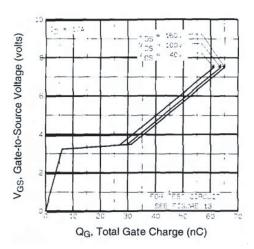


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

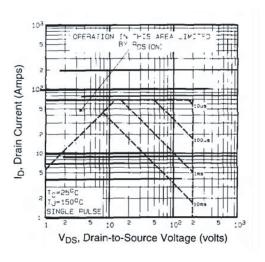


Fig. 8 - Maximum Safe Operating Area



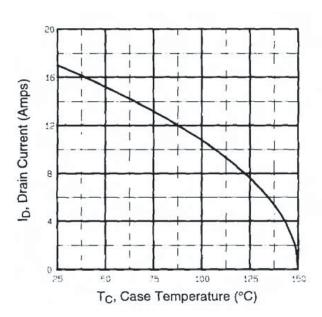


Fig. 9 - Maximum Drain Current vs. Case Temperature

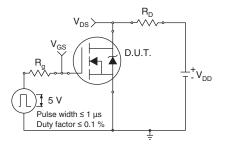


Fig. 10a - Switching Time Test Circuit

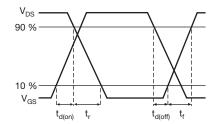


Fig. 10b - Switching Time Waveforms

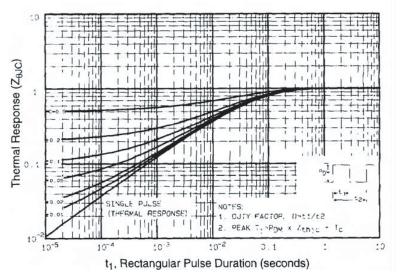


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

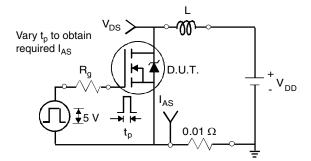


Fig. 12a - Unclamped Inductive Test Circuit

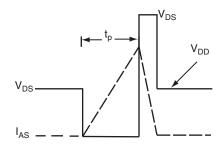


Fig. 12b - Unclamped Inductive Waveforms



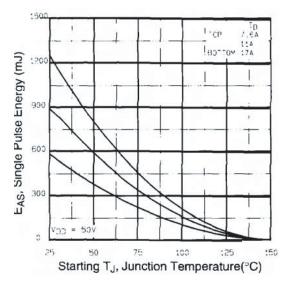


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

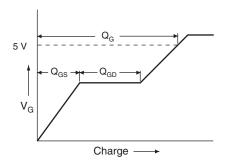


Fig. 13a - Basic Gate Charge Waveform

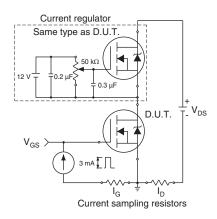
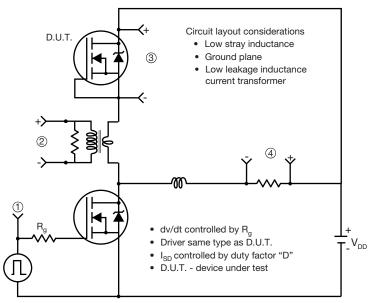


Fig. 13b - Gate Charge Test Circuit



Peak Diode Recovery dv/dt Test Circuit



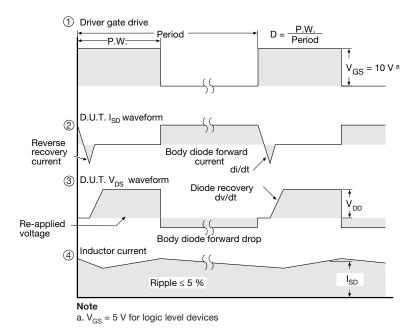


Fig. 14 - For N-Channel

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